

# Final Product/Process Change Notification Document #:FPCN23658ZO Issue Date:21 Feb 2022

Title of Change:	Wafer fab transfer to onsemi Gresham, Oregon USA from onsemi Fab2, Oudenaarde, Belgium related to Fab2 sale	
Proposed Changed Material First Ship Date:	28 Aug 2022 or earlier if approved by customer	
Current Material Last Order Date:	31 Mar 2022 #PD24322Z  Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.	
Current Material Last Delivery Date:	27 Aug 2022 The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory	
Product Category:	Active components – Integrated circuits	
Contact information:	Contact your local onsemi Sales Office or Jelle.Genne@onsemi.com	
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order.  Sample requests are to be submitted no later than 45 days after publication of this change notification.  Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Sample Availability Date:	07 Mar 2022	
PPAP Availability Date:	11 Apr 2022	
Additional Reliability Data:	Contact your local onsemi Sales Office or Catherine.DeKeukeleire@onsemi.com	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com.	
Change Category		
Category	Type of Change	
Packing/Shipping	Packing/shipping specification change	
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor, New wafer diameter	
Equipment	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.	
Data Sheet	Change of datasheet parameters/electrical specification (min./max./typ. values) and/or AC/DC specification	
Process - Assembly	Change of mold compound, Change in process technology (e.g., die attach, bonding, moulding, plating, trim and form, lead frame preperation,), Change in critical dimensions of package, Change in leadframe dimensions, Change of direct material supplier, Change of product marking	

TEM001794 Rev. F Page 1 of 4



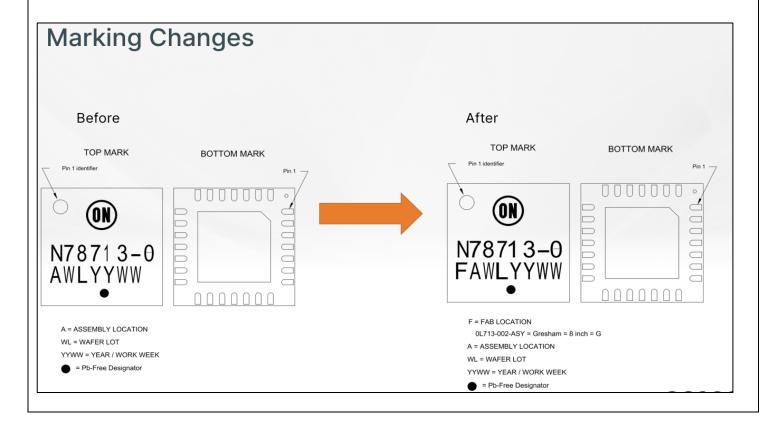
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### **Description and Purpose:**

Wafer fab transfer to onsemi Gresham, Oregon USA from onsemi Fab2, Oudenaarde, Belgium related to Fab2 sale. Change of leadframe and mold compound are also included. Part marking will be adjusted. Datasheet will be updated.

	Before Change Description	After Change Description
Fab Site transfer	onsemi Fab2, Oudenaarde, Belgium 6inch	onsemi Gresham, Oregon USA 8inch
LeadFrame	FR0630 (LF 24L QFN5x5 MM 0.65 MM. Pitch SFS)	FR1192 (LF 24L QFN5x5 MM 0.65 MM. Pitch SLP)
Mold Compound	G770HCD	G700LTD
Part Marking	Without Fab Indicator	With Fab Indicator
Data sheet	Revision 1	Revision 2

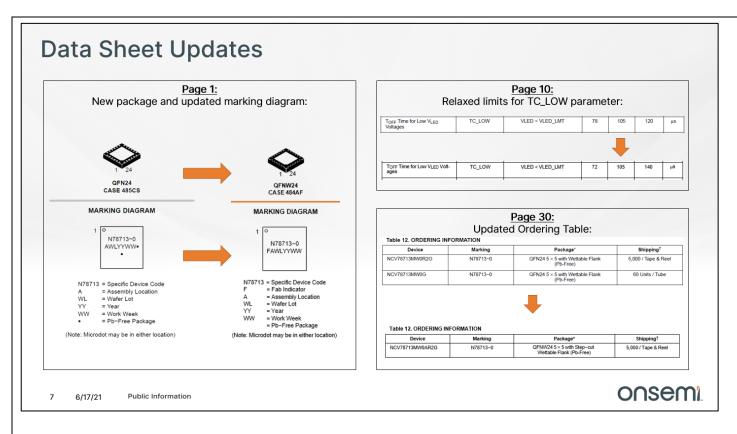


TEM001794 Rev. F Page 2 of 4



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Document #:FPCN23658ZO Issue Date:21 Feb 2022



Reason / Motivation for Change:	Quality improvement			
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded.  No anticipated impacts.			
Sites Affected:				
onsemi Sites		External Foundry/Subcon Sites		
onsemi Oudenaarde, Belgium		UTAC, Thailand		
onsemi, Gresham United States				
Marking of Parts/ Traceability of Change:	Traceability guaranteed by datecode			

TEM001794 Rev. F Page 3 of 4



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Document #:FPCN23658ZO Issue Date:21 Feb 2022

### **Reliability Data Summary:**

### NOTE: AEC-1pager is attached.

To view attachments:

- 1. Download pdf copy of the PCN to your computer
- 2. Open the downloaded pdf copy of the PCN
- 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
- 4. Then click on the attached file

## **Electrical Characteristics Summary:**

Electrical characteristics are not impacted.

#### **List of Affected Parts:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Current Part Number	New Part Number	Qualification Vehicle
NCV78713MW0R2G	NCV78713MWA0R2G	0L713-600

TEM001794 Rev. F Page 4 of 4